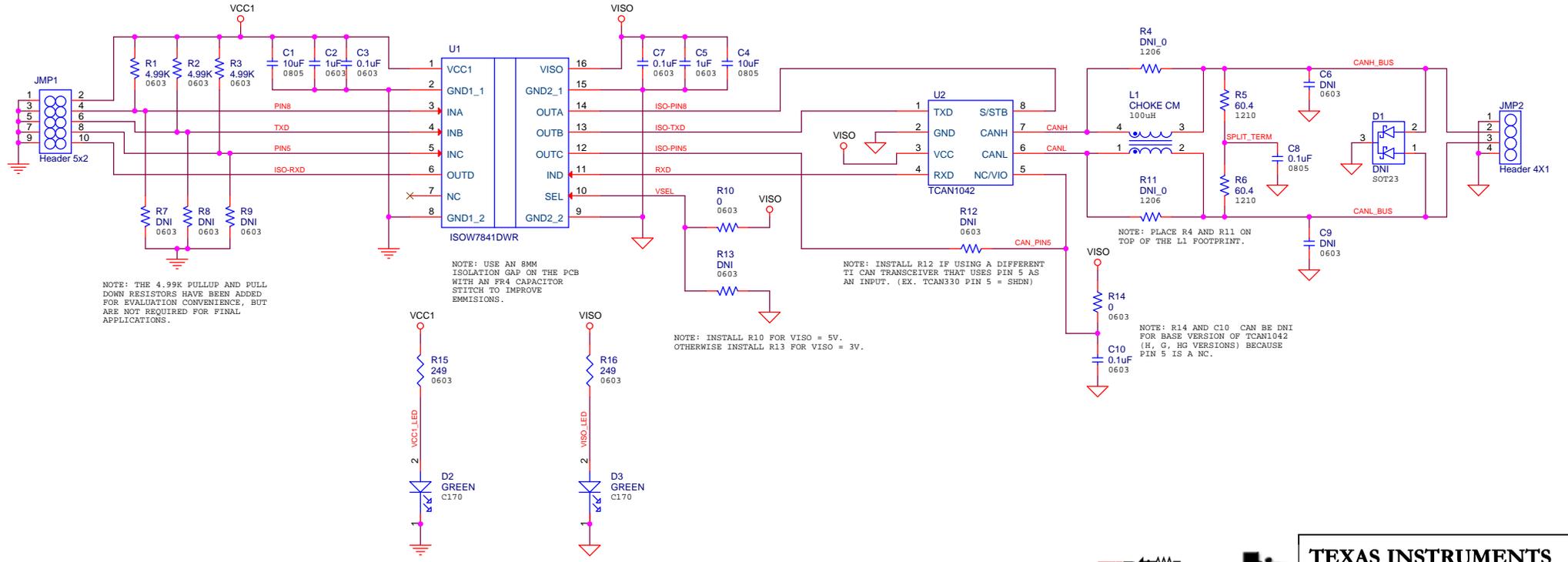


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TEXAS INSTRUMENTS

SCHEMATIC TITLE
ISOLATED CAN MODULE USING INTEGRATED POWER DIGITAL ISOLATOR REFERENCE DESIGN

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